

2A, 200V - 1000V High Efficient Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Low power loss, high efficiency
- Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- Freewheeling application

MECHANICAL DATA

- Case: SOD-128
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.028g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
I_F	2	A
V_{RRM}	200 - 1000	V
I_{FSM}	60	A
T_{JMAX}	150	°C
Package	SOD-128	
Configuration	Single die	



SOD-128



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)							
PARAMETER	SYMBOL	HS2DFS	HS2GFS	HS2JFS	HS2KFS	HS2MFS	UNIT
Marking code on the device		HS2DFS	HS2GFS	HS2JFS	HS2KFS	HS2MFS	
Repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	140	280	420	560	700	V
Forward current	I_F	2					A
Surge peak forward current, single half sine-wave superimposed on rated load	$t = 8.3\text{ms}$	60					A
	$t = 1.0\text{ms}$	120					A
Junction temperature	T_J	-55 to +150					°C
Storage temperature	T_{STG}	-55 to +150					°C

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\theta JL}$	17	$^{\circ}\text{C/W}$
Junction-to-ambient thermal resistance	$R_{\theta JA}$	53	$^{\circ}\text{C/W}$
Junction-to-case thermal resistance	$R_{\theta JC}$	21	$^{\circ}\text{C/W}$

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS ($T_A = 25^{\circ}\text{C}$ unless otherwise noted)							
PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT	
Forward voltage ⁽¹⁾	HS2DFS	$I_F = 1.0\text{A}, T_J = 25^{\circ}\text{C}$	V_F	0.81	-	V	
		$I_F = 2.0\text{A}, T_J = 25^{\circ}\text{C}$		0.87	1.00	V	
		$I_F = 1.0\text{A}, T_J = 125^{\circ}\text{C}$		0.67	-	V	
		$I_F = 2.0\text{A}, T_J = 125^{\circ}\text{C}$		0.74	0.82	V	
	HS2GFS	$I_F = 1.0\text{A}, T_J = 25^{\circ}\text{C}$		0.90	-	V	
		$I_F = 2.0\text{A}, T_J = 25^{\circ}\text{C}$		0.99	1.30	V	
		$I_F = 1.0\text{A}, T_J = 125^{\circ}\text{C}$		0.76	-	V	
		$I_F = 2.0\text{A}, T_J = 125^{\circ}\text{C}$		0.86	0.96	V	
	HS2JFS	$I_F = 1.0\text{A}, T_J = 25^{\circ}\text{C}$		1.00	-	V	
		$I_F = 2.0\text{A}, T_J = 25^{\circ}\text{C}$		1.10	1.70	V	
		$I_F = 1.0\text{A}, T_J = 125^{\circ}\text{C}$		0.80	-	V	
		$I_F = 2.0\text{A}, T_J = 125^{\circ}\text{C}$		0.92	1.10	V	
	HS2KFS HS2MFS	$I_F = 1.0\text{A}, T_J = 25^{\circ}\text{C}$		1.30	-	V	
		$I_F = 2.0\text{A}, T_J = 25^{\circ}\text{C}$		1.48	1.70	V	
		$I_F = 1.0\text{A}, T_J = 125^{\circ}\text{C}$		0.94	-	V	
		$I_F = 2.0\text{A}, T_J = 125^{\circ}\text{C}$		1.11	1.23	V	
Reverse current @ rated V_R ⁽²⁾		$T_J = 25^{\circ}\text{C}$	I_R	-	1	μA	
		$T_J = 125^{\circ}\text{C}$		-	80	μA	
Reverse recovery time	HS2DFS HS2GFS	$I_F = 0.5\text{A}, I_R = 1.0\text{A},$ $I_{rr} = 0.25\text{A}$	t_{rr}	-	50	ns	
	HS2JFS HS2KFS HS2MFS			-	75	ns	
Junction capacitance	HS2DFS		1MHz, $V_R = 4.0\text{V}$	C_J	32	-	pF
	HS2GFS				25	-	pF
	HS2JFS	17			-	pF	
	HS2KFS HS2MFS	12			-	pF	

Notes:

1. Pulse test with $PW = 0.3\text{ms}$
2. Pulse test with $PW = 30\text{ms}$

ORDERING INFORMATION

ORDERING CODE⁽¹⁾	PACKAGE	PACKING
HS2xFS	SOD-128	14,000 / Tape & Reel

Notes:

1. “x” defines voltage from 200V(HS2DFS) to 1000V(HS2MFS)

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

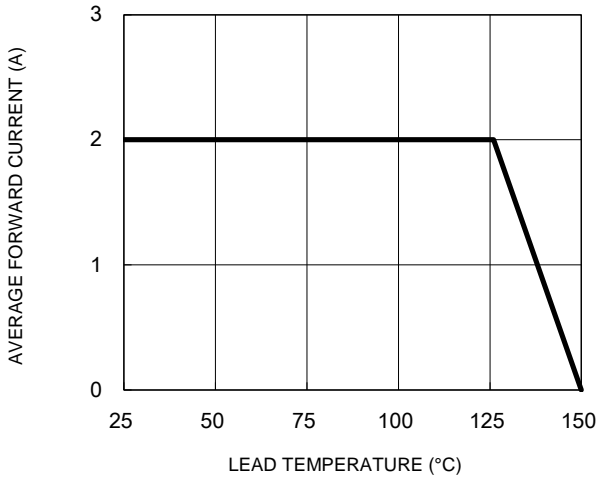


Fig.2 Typical Junction Capacitance

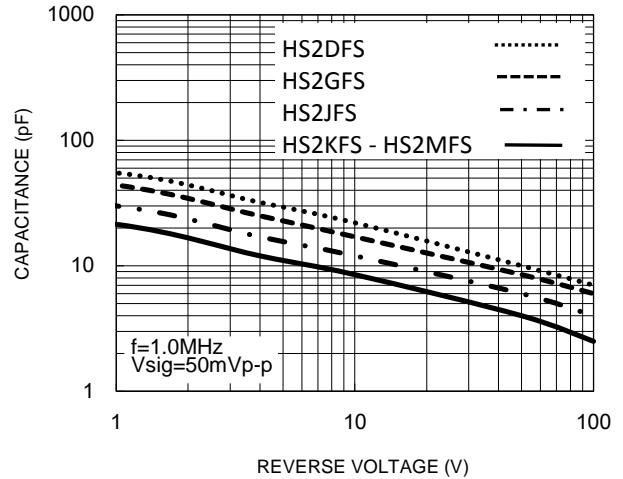


Fig.3 Typical Reverse Characteristics

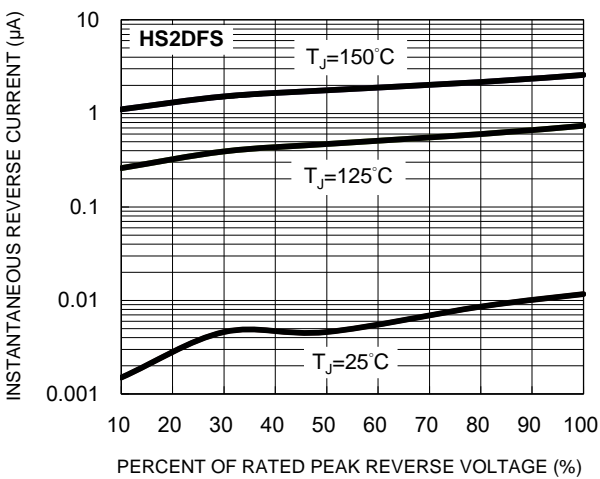


Fig.4 Typical Forward Characteristics

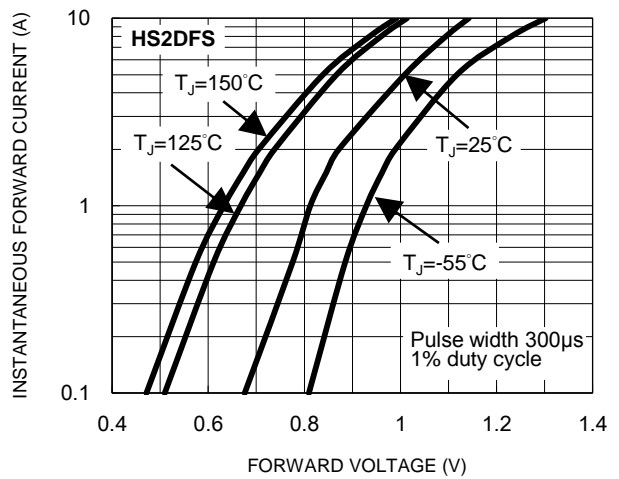


Fig.5 Typical Reverse Characteristics

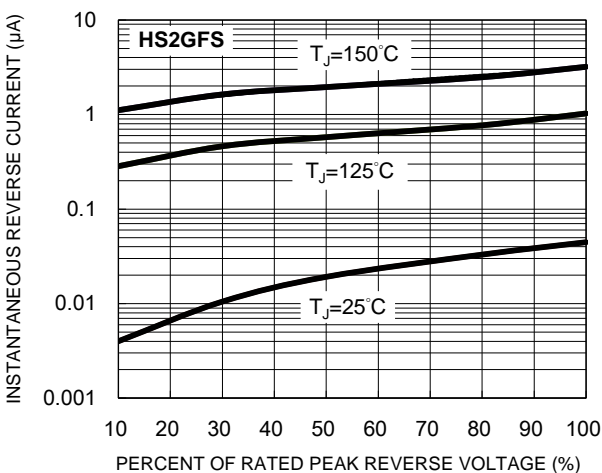
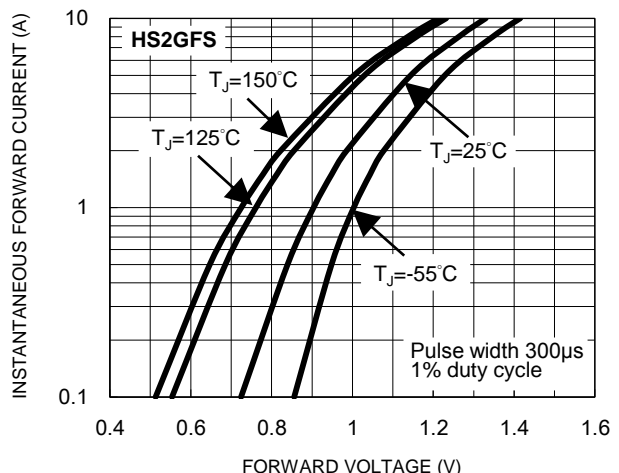


Fig.6 Typical Forward Characteristics



CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.7 Typical Reverse Characteristics

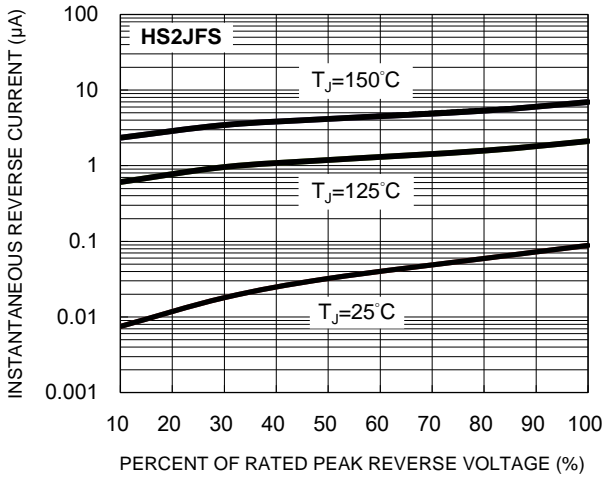


Fig.8 Typical Forward Characteristics

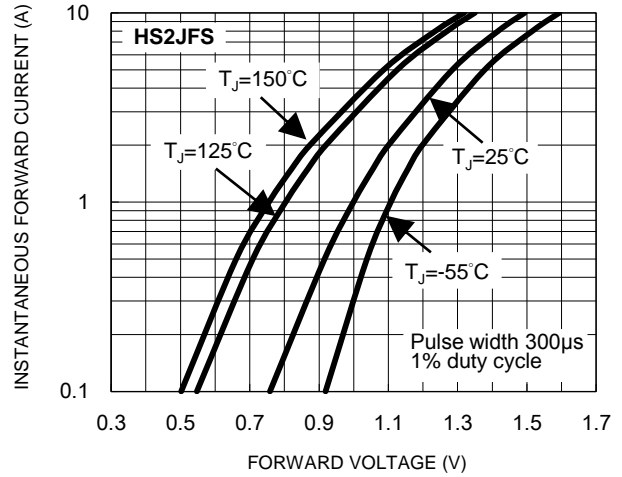


Fig.9 Typical Reverse Characteristics

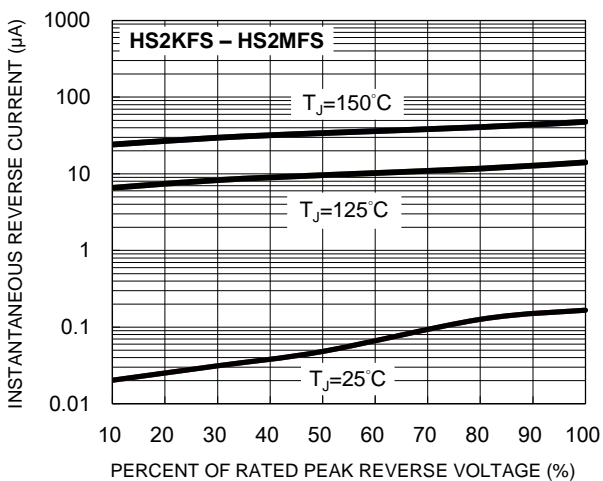


Fig.10 Typical Forward Characteristics

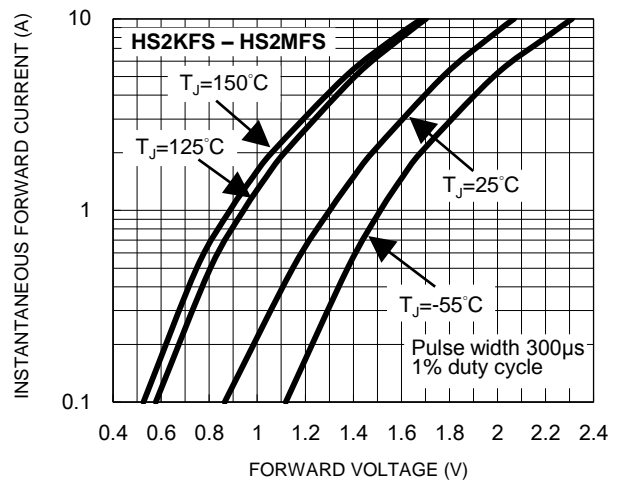
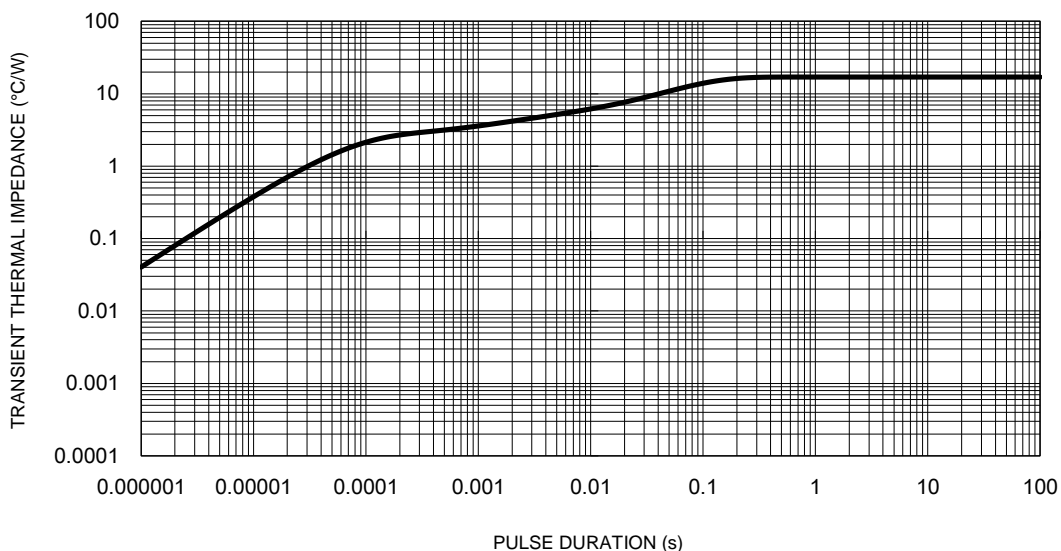
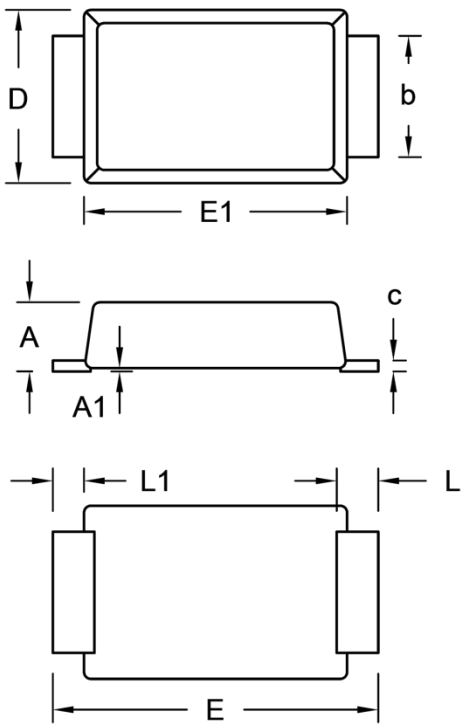


Fig.11 Typical Transient Thermal Impedance



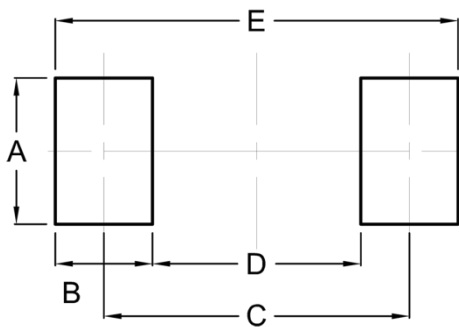
PACKAGE OUTLINE DIMENSIONS

SOD-128



DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	0.90	1.10	0.035	0.043
A1	0.00	0.10	0.000	0.004
b	1.60	1.90	0.063	0.075
c	0.10	0.22	0.004	0.009
D	2.30	2.70	0.091	0.106
E	4.40	5.00	0.173	0.197
E1	3.60	4.00	0.142	0.157
L	0.40	0.80	0.016	0.031
L1	0.30	0.60	0.012	0.024

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.10	0.083
B	1.40	0.055
C	4.40	0.173
D	3.00	0.118
E	5.80	0.228

MARKING DIAGRAM



P/N = Marking Code
 YW = Date Code
 F = Factory Code

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